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(2013.01)(71) Applicant: **Innolux Corporation**, Miao-Li County
(TW)(72) Inventors: **Yi-Hung Lin**, Miao-Li County (TW);
Hsiu-Yi Tsai, Miao-Li County (TW);
Chin-Lung Ting, Miao-Li County
(TW); **Chung-Kuang Wei**, Miao-Li
County (TW)(73) Assignee: **Innolux Corporation**, Miao-Li County
(TW)

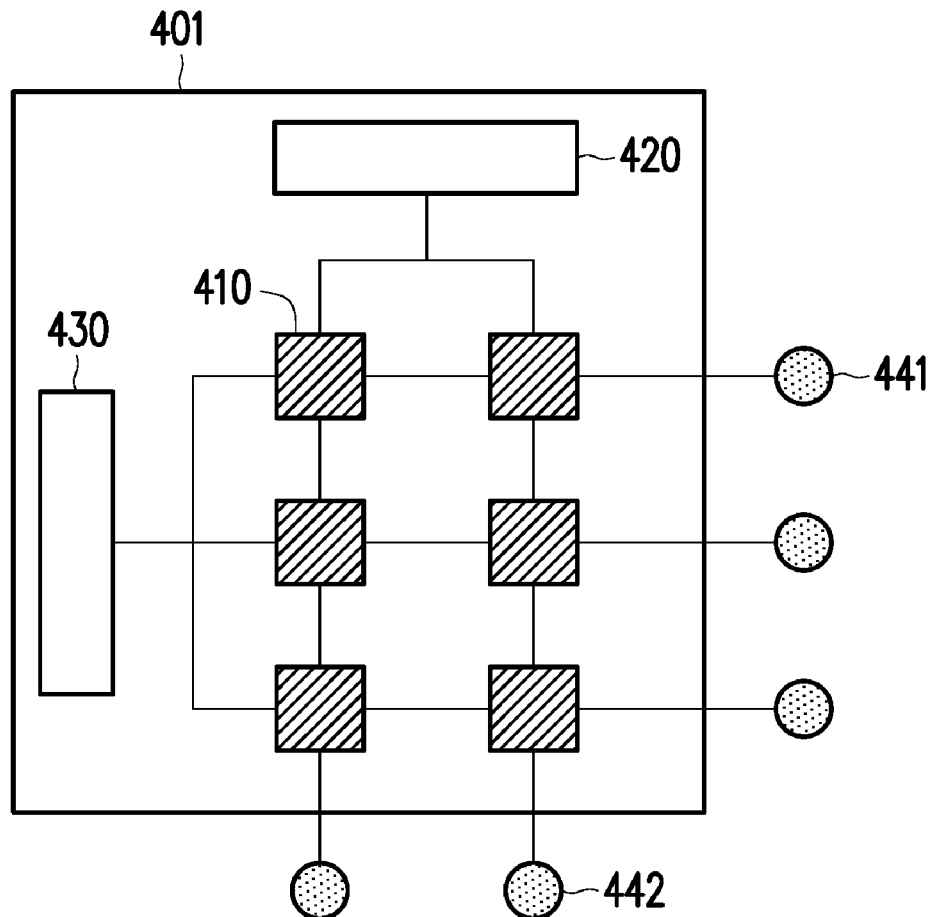
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ABSTRACT

A manufacturing method of an electronic device is provided. The manufacturing method of the electronic device includes following steps: providing a substrate; bonding at least one electronic component to the substrate, wherein the at least one electronic component is mainly driven by a reverse bias in an operating mode; applying a forward bias to the at least one electronic component, and determining whether the at least one electronic component is normal or failed; and transporting the substrate configured with the at least one electronic component determined to be normal to a next production site or repairing the at least one electronic component determined to be failed.

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